

## PROCESS/PRODUCT CHANGE NOTICE

<b>Issuing Division:</b>	Operations
<b>Part Family Affected:</b>	N/A
<b>Part Numbers Affected:</b>	GN4124-CBE3 and GN4121-CBE3
<b>Date Code / Lot No.:</b>	N/A
<b>Type of Change:</b>	<input checked="" type="checkbox"/> Type 1: Process <input type="checkbox"/> Type 2: Product Features and/or Specifications <input type="checkbox"/> Type 3: Product Obsolete with/without replacement <input type="checkbox"/> Type 4: Recommended Applications Circuit Changes <input type="checkbox"/> Type 5: Datasheet Only <input type="checkbox"/> Type 6: Shipping/Packing Method
<b>Title of Change:</b>	<b>Bond wire material change from gold to copper</b>
<b>Date of Issue:</b>	July 15 <sup>th</sup> 2013
<b>Effective Date:</b>	October 15 <sup>th</sup> 2013
<b>Authorized by:</b>	Dwayne Johnson, Manager of Product Engineering, Operations
<b>PCN Number:</b>	PCN-000163
<b>PCN Type:</b>	<input type="checkbox"/> Minor <input checked="" type="checkbox"/> Major
<b>Datasheet Revision:</b>	N/A

### DESCRIPTION OF CHANGE:

The GN4124-CBE3 and GN4121-CBE3 products are currently assembled using gold bond wires internal to the IC package. This bond wire material will be changed from gold to copper to be consistent with currently-common assembly processes and materials.

Devices with copper wire bonding will have the date code '1326' and forward.

Samples and reliability report are available upon request.

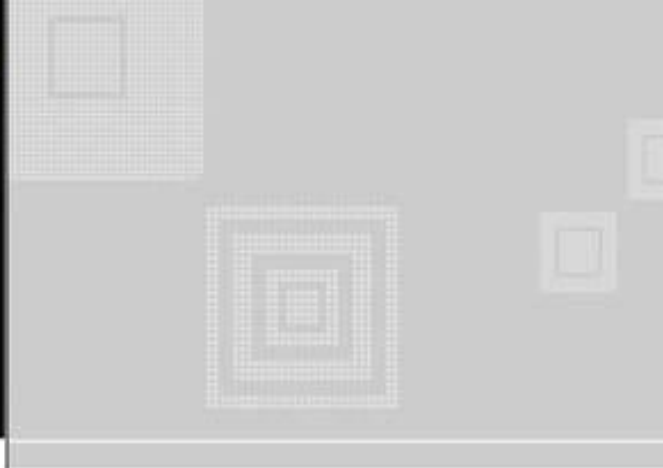
### EFFECT OF CHANGE:

The customer will experience no change to the form, fit, or function of the final product. No critical parameters are affected by this change. There are no other changes included in this PCN besides the bond wire material change.

### RECOMMENDED CUSTOMER ACTION(S):

No customer actions are required.

**FOR FURTHER INFORMATION & WORLDWIDE SALES COVERAGE:** <http://www.semtech.com/contact/index.html#support>



# GIGOPTIX F2691G-01 LBGA 17X17 Cu Wire Bond Evaluation

Prepared by

ASE Group  
Assembly Cu Wire CPE  
Dec. 2012

# Purpose



- Customer “GIGOPTIX” would like to do wire bond feasibility study in LBGA 17X17 256L package (Device: F2691G-01) with 18um Cu wire



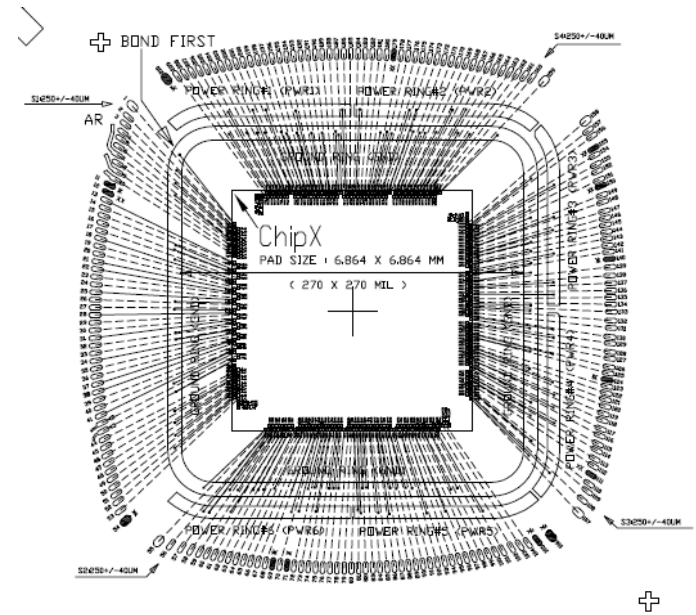
# Package configuration and BOM

- Device information

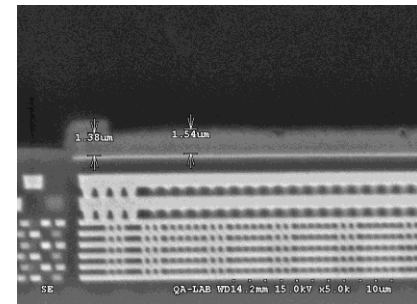
- PKG: LPGA 17X17
- Device: F2691G-01
- B.P.P: 60 um
- B.P.O: 53x53 um
- Bond pad Al thickness: 1.54um

- W/B material control

- Cu Wire: 18um Pd coated



B/D layout

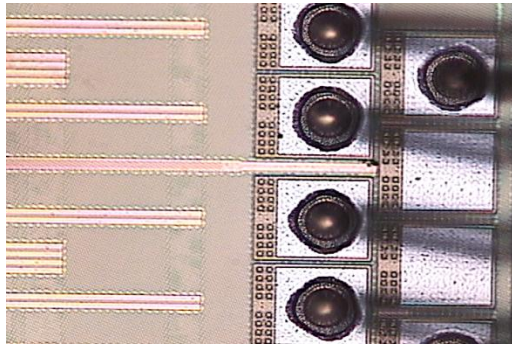


Al thickness

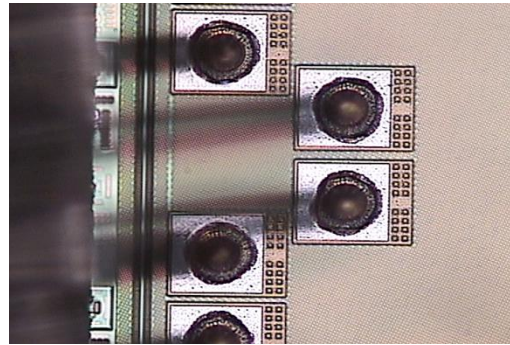


# WB Response for Ball Size

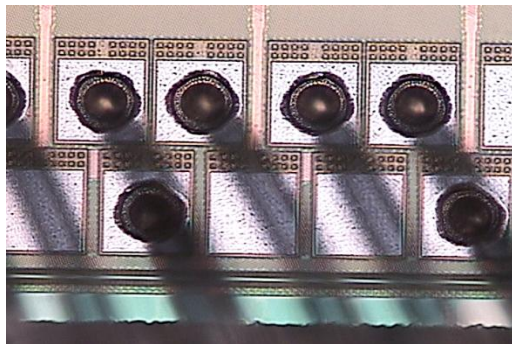
## Ball Size



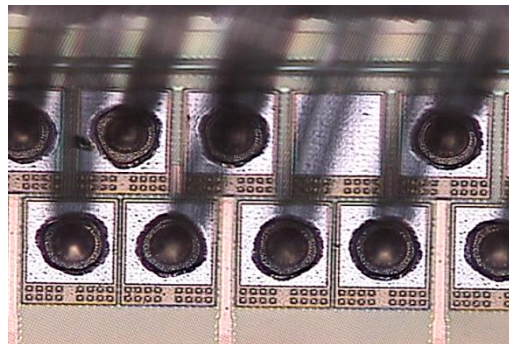
Left



Right



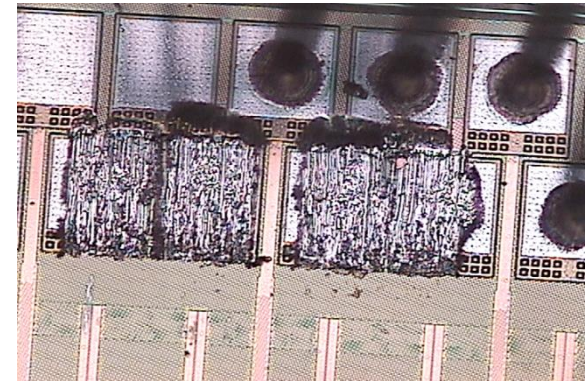
Down



Up

## Ball Shear Data

Station	Value_item	Spec limit	SS	MAX	MIN	AVG	SIGMA	Cpk
WIRE BOND	BS_CU	5.000/	10	22.85	22.04	22.582	0.25	23.462



Ball size / ball height is controlled within avg. 37-42um and avg. 8-12um.

Ball Shear strength can pass test criteria

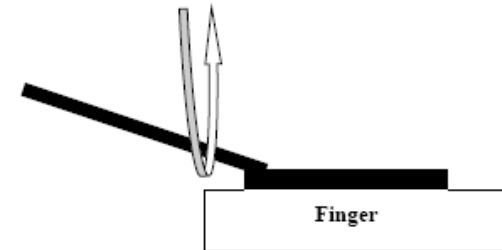


# Bond ability Evaluation

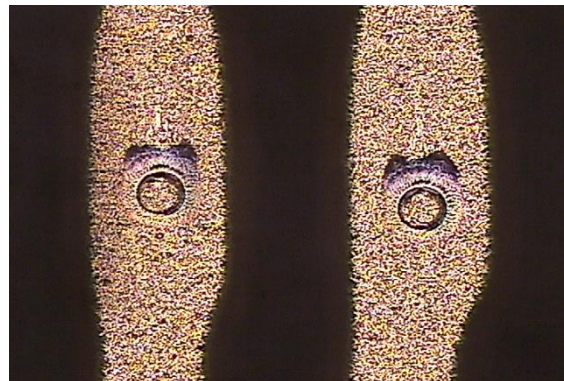
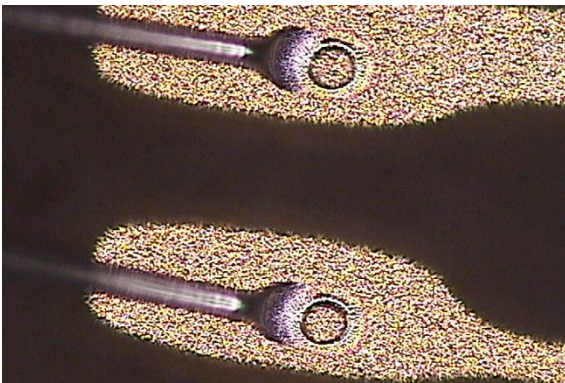
## ● Stitch pull test

Station	DCOP	Value_item	Spec limit	SS	MAX	MIN	AVG	SIGMA	Cpk
WIRE BOND	WP_02	GROUND_CU	3.000/	10	7.99	6.62	7.349	0.351	4.134

Stitch pull strength can pass test criteria



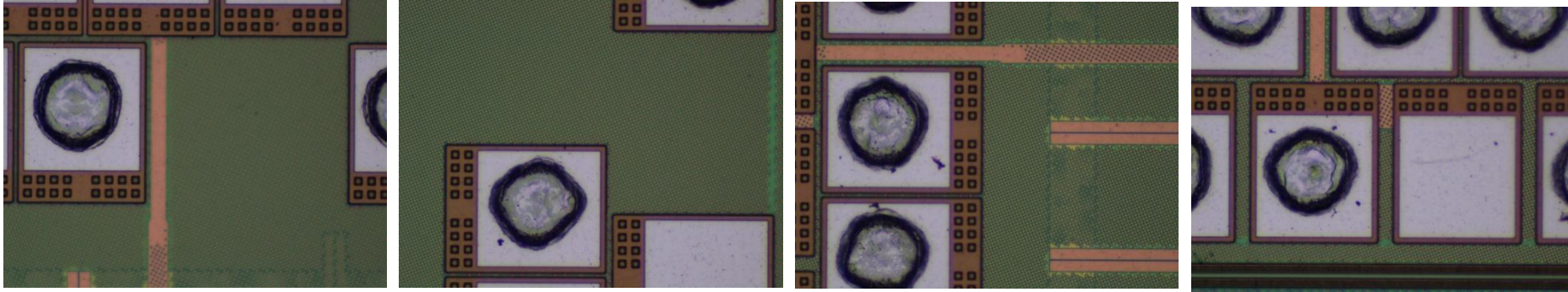
Stitch pull break mode acceptable



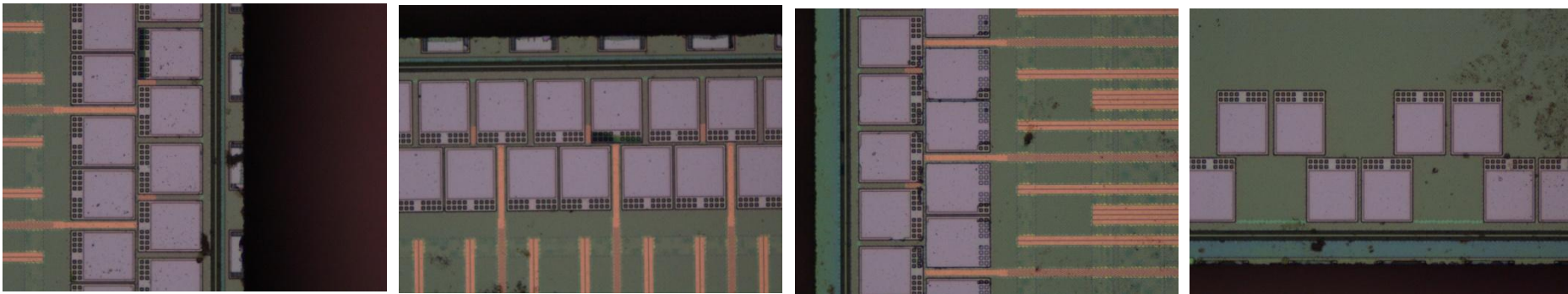


# WB Response for De-layer & IMC Test

## IMC



## Delayer



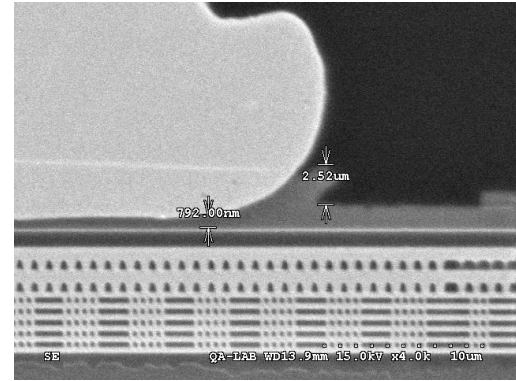
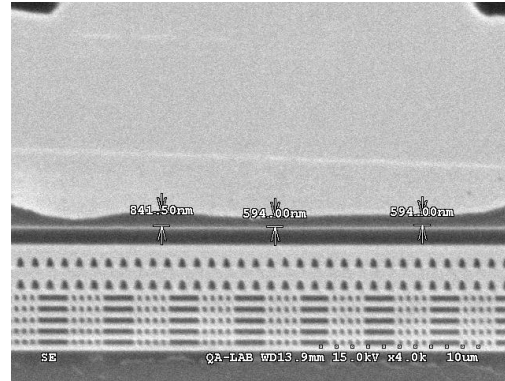
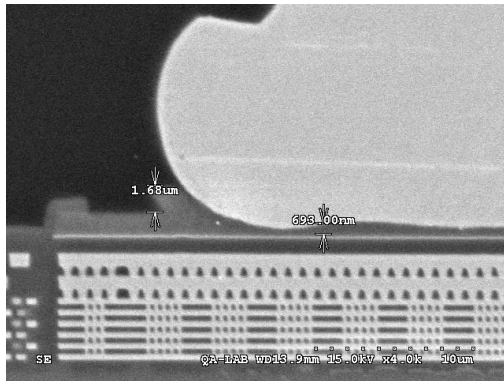
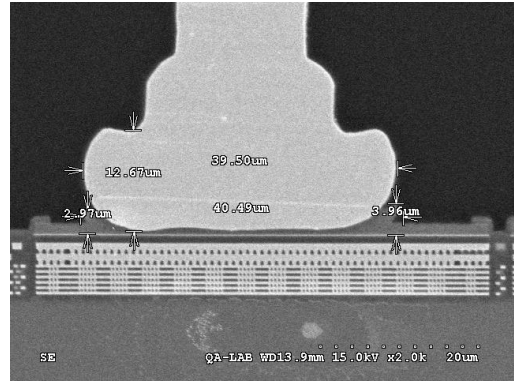
IMC is passed ASEK spec(80%) and delayer test is found no any cratering.



# Wire Bond Buy Off - Cross-section Confirmation



## Ball bond confirmation



There is Al remaining under Cu bonding ball and no IMD crack issue be found.





# Conclusion

- Confirm run pass all bond-ability test



Thank you for your listening  
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ASE GROUP

ASE Confidential / Security-B  
QA LABORATORY

Date: 2013/05/29

## RELIABILITY TEST REPORT

**CUSTOMER: GIGOPTIX**

**PACKAGE TYPE: LPGA (17x17) 256L**

**REPORT NO.: RT-130529-CR01**

**DISTRIBUTION:**

REQUESTED BY: Luvill Villacin

MANAGER: Hsini Lee

Prepared By: Wayne Chy

Checked By: Denni Lu

Approved By: Denni Lu

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## I. Purpose

F2691G-01 - Cu Wire.

## II. Conclusion

- (1) No failure was found after reliability tests based on specified criteria.
- (2) Based on above, the test result can be judged “PASS”.

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### III. Package Profile

ASE Schedule No.	03CC14
Device No.	F2691G-01
Lot No.	QL65L-CQ
Package Type	LBGA
Package Size	17x17 mm
Ball_Lead Count	256
Pad Size	6864x6864 mic
Ball_Lead Pitch	1 mm
Ball_Lead Width	0.5 mm
Solder Ball Composition	95.5Sn/4.0Ag/0.5Cu
Wire Type	Copper Wire
Wire Diameter	18_CU_PD
Epoxy Type (Die attach)	2100A
Compound Type	CEL-9750ZHF10AKLE
SUB_L/F Vendor	ASEE-SH
SUB_L/F Part No.	1207415111
SUB_L/F Layer	4
Case ID	133E88/133E89

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## IV. Summary Data of Reliability Test

### (1) Preconditioning

1-1 Convection reflow profiles are shown in figure 1.

1-2 SAT pictures are shown in figure 2.

#### 1-3 SAT Criteria

Item	Before Precondition	After Precondition	Spec No.
Die Top	Reject, if > 0%	Reject, if > 0%	62-31-0000-0369
Epoxy	Reject, if > 0%	Reject, if > 0%	
Substrate Area	Reject, if > 0%	Reject, if > 0%	

#### 1-4 F/T Parameters

Procedure	Condition/Criteria	Spec No.
Function Test	Program name : GN41242_FT_E	74-31-0050-0002

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**1-5 Reflow Criteria**

<b>Spec No.</b>	<b>62-31-0000-0415</b>
<b>Peak temp</b>	<b>265°C(+0/-5°C)</b>
<b>Preheat</b>	<b>60~120sec(150~200°C)</b>
<b>Average Ramp-up Rate</b>	<b>≤3.0°C/sec (217°C~Peak)</b>
<b>Time Maintained Above</b>	<b>60~150sec(above 217°C)</b>
<b>Time Within 5°C Of Actual Peak Temperature</b>	<b>&gt;30sec(above 255°C)</b>
<b>Ramp-down Rate</b>	<b>&lt;6°C/sec(Peak ~217°C)</b>
<b>Time 25°C to Peak Temperature</b>	<b>8 minutes max.</b>

**1-6 Precondition Test**

<b>Test Condition</b>		<b>Visual Inspection</b>	<b>F/T Test</b>	<b>SAT Inspection</b>
<b>JEDEC 22-A113 Level 3 30°C/60%RH 192 HRS</b>	<b>Before Precondition</b>	<b>0/154</b>	<b>-</b>	<b>0/154</b>
	<b>After Precondition</b>	<b>0/154</b>	<b>0/154</b>	<b>0/154</b>

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**(2) Environmental Stress Test—Following Precondition**

Test Item	Test Condition	Test Interval	Visual Inspection	F/T Test
Temperature Cycling Test	JEDEC 22-A104 -65°C~150°C	1000 Cycles	0/77	0/77
HAST Test <b>(No Bias)</b>	JEDEC 22-A118 130°C/85%RH 33.5PSIA	96 Hours	0/77	0/77

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### (3) Environmental Stress Test--No Precondition

Test Item	Test Condition	Test Interval	Visual Inspection	F/T Test
High Temperature Storage Test	JEDEC 22-A103 150°C	1000 hours	0/77	0/77

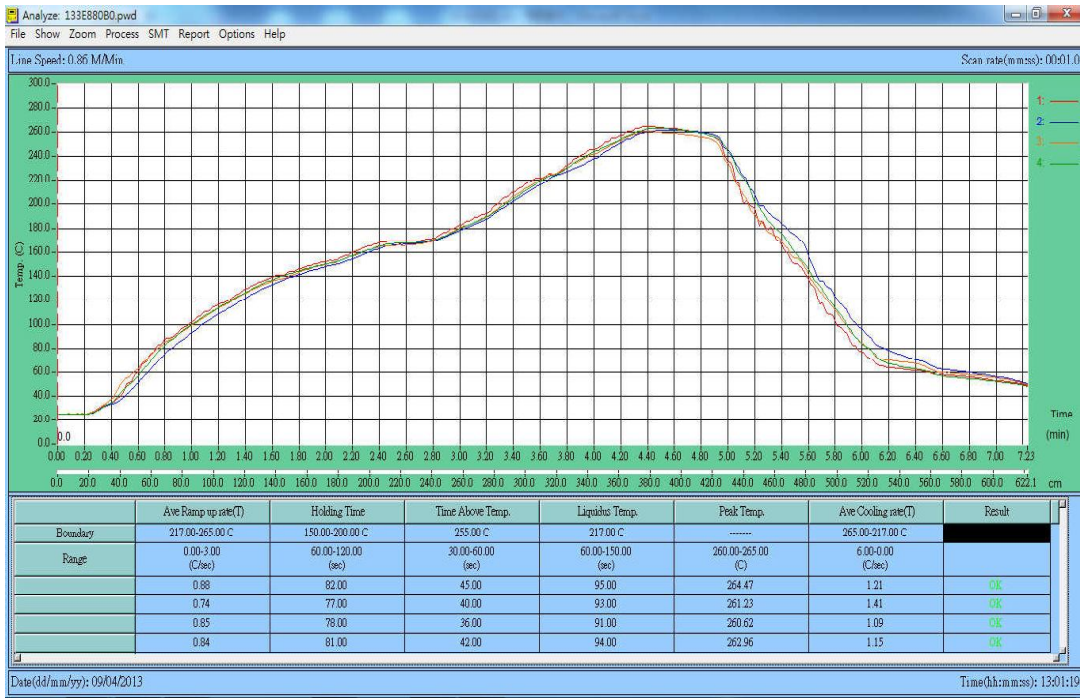
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Figure 1. Reflow Profile

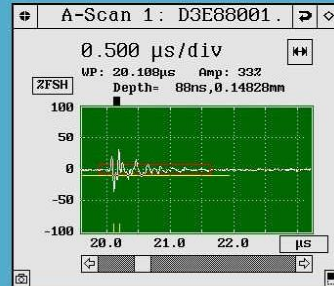
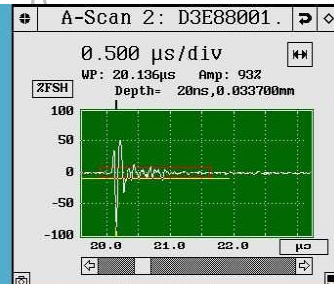
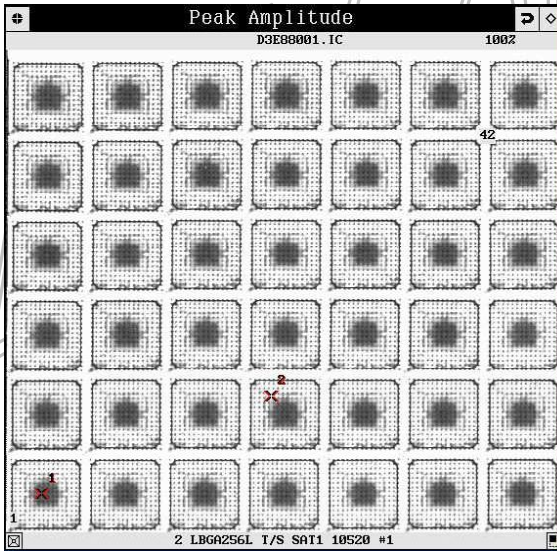
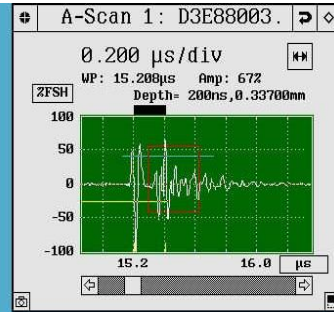
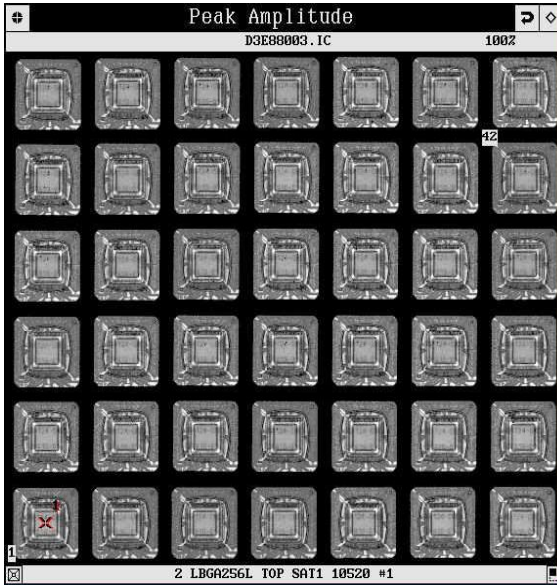


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## Figure 2. SAT Images

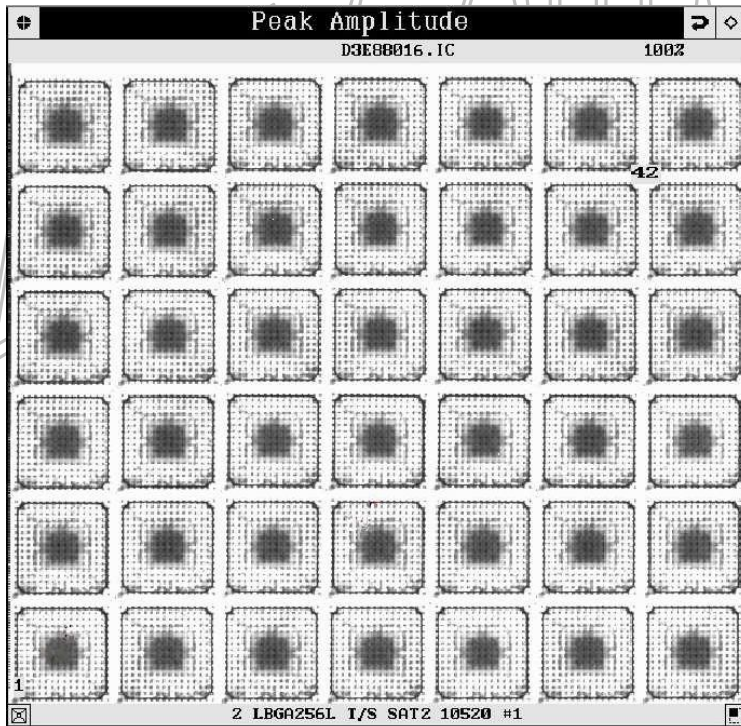
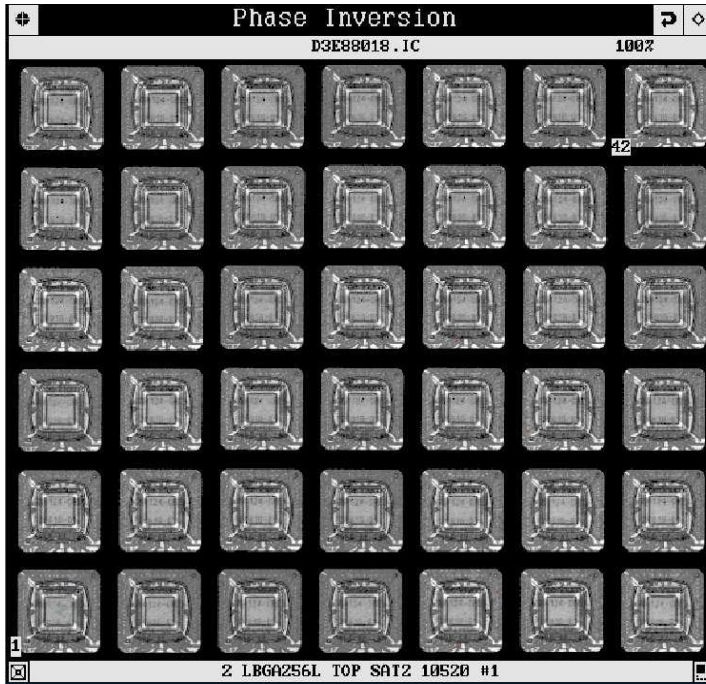
### 2-1. Befor Precondition



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### 2-2. After Precondition



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PCIe_max				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
JTAG_max				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
MBIST_max				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
PLL_max				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
PCIe_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
JTAG_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
MBIST_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
PLL_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
SCAN_SR_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
SCAN_flush_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
SCAN_full_min				Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass		Pass	Pass	Pass	Pass	Pass	Pass	Pass		
TEST RESULT				PASSED	PASSED	PASSED	PASSED		PASSED	PASSED	PASSED	PASSED	PASSED		PASSED	PASSED	PASSED	PASSED	PASSED	PASSED	PASSED		